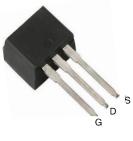


# **IRF1104L-VB Datasheet** N-Channel 40-V (D-S) 175 °C MOSFET

| PRODUCT SUMMARY          |                                 |                    |                       |  |
|--------------------------|---------------------------------|--------------------|-----------------------|--|
| V <sub>(BR)DSS</sub> (V) | r <sub>DS(on)</sub> (∧)         | I <sub>D</sub> (A) | Q <sub>g</sub> (Typ.) |  |
| 40                       | 0.005 at V <sub>GS</sub> = 10 V | 100                | 95                    |  |

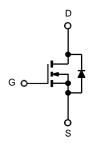
### TO-262



Top View

### **FEATURES**

- Trench Power MOSFET
- 175 °C Junction Temperature
- High Threshold Voltage at High Temperature COMPLIANT



N-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b> $T_C = 25$ °C, unless otherwise noted |                                     |                                   |                  |      |  |
|---|-------------------------------------|-----------------------------------|------------------|------|--|
| Parameter   |                                     | Symbol                            | Limit            | Unit |  |
| Drain-Source Voltage  |                                     | V <sub>DS</sub>                   | 40               | - V  |  |
| Gate-Source Voltage   |                                     | V <sub>GS</sub>                   | 20               |      |  |
| Continuous Drain Current (T <sub>.1</sub> = 175 °C)                   | T <sub>C</sub> = 25 °C              | - I <sub>D</sub>                  | 110              |      |  |
| Continuous Drain Current (1) = 173 C)                                 | T <sub>C</sub> = 125 °C             |                                   | 70               |      |  |
| Pulsed Drain Current  |                                     | I <sub>DM</sub>                   | 300              | - A  |  |
| Avalanche Current   |                                     | I <sub>AR</sub>                   | 50               |      |  |
| Repetitive Avalanche Energy <sup>a</sup>                              | L = 0.1 mH                          | E <sub>AR</sub>                   | 125              | mJ   |  |
|   | T <sub>C</sub> = 25 °C              | Р                                 | 150 <sup>b</sup> |      |  |
| Maximum Power Dissipation <sup>a</sup>                                | T <sub>A</sub> = 25 °C <sup>c</sup> | P <sub>D</sub>                    | 3.75             | - W  |  |
| Operating Junction and Storage Temperature Range                      |                                     | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 175      | °C   |  |

| THERMAL RESISTANCE RATINGS |                        |                   |       |      |
|----------------------------|------------------------|-------------------|-------|------|
| Parameter                  |                        | Symbol            | Limit | Unit |
| Junction-to-Ambient        | PCB Mount <sup>c</sup> | R <sub>thJA</sub> | 40    | °C/W |
| Junction-to-Case           |                        | R <sub>thJC</sub> | 1     | 0/11 |

Notes:

a. Duty cycle  $\leq$  1 %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).

| <b>SPECIFICATIONS</b> $T_J = 25^{\circ}$      | C, unless ot         | herwise noted   |      |        |       |      |  |
|---|----------------------|---|------|--------|-------|------|--|
| Parameter                                     | Symbol               | Test Conditions   | Min. | Тур.   | Max.  | Unit |  |
| Static  |                      |   |      |        |       |      |  |
| Drain-Source Breakdown Voltage                | V <sub>(BR)DSS</sub> | $V_{DS} = 0 V, I_D = 250 \mu A$   | 40   |        |       | - v  |  |
| Gate-Threshold Voltage                        | V <sub>GS(th)</sub>  | $V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$  | 1.0  | 2.0    | 4.0   |      |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>     | $V_{DS} = 0 V, V_{GS} = \pm 20 V$   |      |        | ± 100 | nA   |  |
| Zero Gate Voltage Drain Current               |                      | $V_{DS} = 40 V, V_{GS} = 0 V$   |      |        | 1     | μΑ   |  |
|   | I <sub>DSS</sub>     | $V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$   |      |        | 50    |      |  |
|   |                      | $V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 \text{ °C}$   |      |        | 250   |      |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>   | $V_{DS} = 5 V, V_{GS} = 10 V$   | 120  |        |       | А    |  |
| Drain-Source On-State Resistance <sup>a</sup> |                      | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A   |      | 0.005  |       |      |  |
|   | r <sub>DS(on)</sub>  | $V_{GS}$ = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 125 °C   |      | 0.008  |       |      |  |
|   |                      | $V_{GS}$ = 10 V, $I_{D}$ = 15 A, $T_{J}$ = 175 °C   |      | 0.0106 |       | 1    |  |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>      | $V_{DS} = 15 \text{ V}, I_{D} = 15 \text{ A}$   | 20   | 50     |       | S    |  |
| Dynamic <sup>b</sup>                          |                      |   |      |        |       |      |  |
| Input Capacitance                             | C <sub>iss</sub>     | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz  |      | 3200   |       | pF   |  |
| Output Capacitance                            | C <sub>oss</sub>     |   |      | 600    |       |      |  |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>     |   |      | 320    |       |      |  |
| Total Gate Charge <sup>c</sup>                | Qg                   |   |      | 95     |       | nC   |  |
| Gate-Source Charge <sup>c</sup>               | Q <sub>gs</sub>      | $V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$  |      | 37     |       |      |  |
| Gate-Drain Charge <sup>c</sup>                | Q <sub>gd</sub>      |   |      | 21     |       |      |  |
| Gate Resistance                               | Rg                   | f = 1.0 MHz   |      | 1.7    |       | ^    |  |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>   |   |      | 20     | 30    | ns   |  |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>       | $V_{DD} = 20 \text{ V}, \text{R}_{\text{L}} = 0.4  \land$ $\text{I}_{\text{D}} \cong 50 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{R}_{\text{g}} = 2.5  \land$ |      | 95     | 145   |      |  |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub>  |   |      | 50     | 75    |      |  |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>       |   |      | 12     | 20    |      |  |
| Source-Drain Diode Ratings and Cha            | racteristics T       | <sub>C</sub> = 25 °C <sup>b</sup>   | I    | 1      |       |      |  |
| Continuous Current                            | I <sub>S</sub>       |   |      |        | 100   | ^    |  |
| Pulsed Current                                | I <sub>SM</sub>      |   |      |        | 300   | — A  |  |
| Forward Voltage <sup>a</sup>                  | V <sub>SD</sub>      | $I_F = 30 \text{ A}, V_{GS} = 0 \text{ V}$  |      | 0.90   | 1.50  | V    |  |
| Reverse Recovery Time                         | t <sub>rr</sub>      | I <sub>F</sub> = 30 A, di/dt = 100 A/µs   |      | 40     | 60    | ns   |  |

Notes:

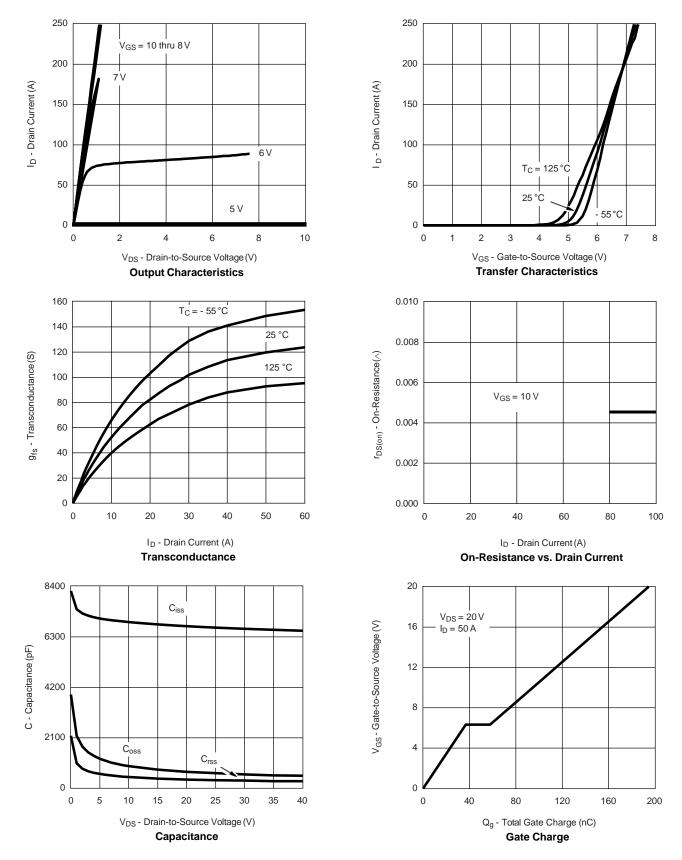
a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing. c. Independent of operating temperature.

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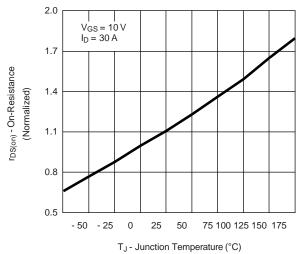




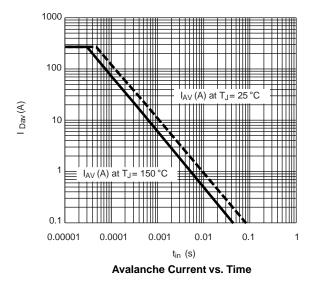


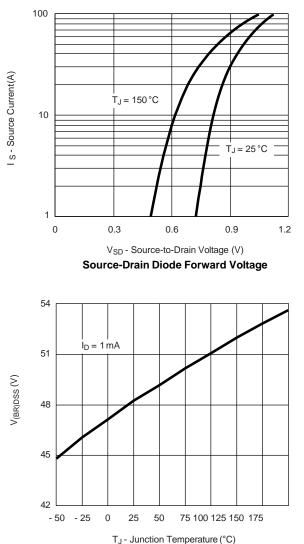


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



On-Resistance vs. Junction Temperature



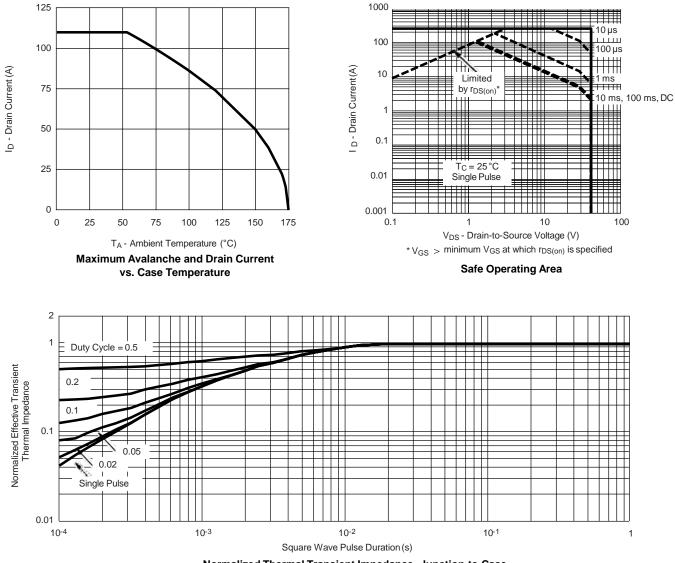


Drain Source Breakdown vs. Junction Temperature

### IRF1104L-VB



#### THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



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